1. Part No. Expression:

WAQ5FD110-RC-10

- (b) (c) (a)
- (d) (e)(f)

(g)

(a) Series Code

(e) Packaging Code

(b) Dimension Code

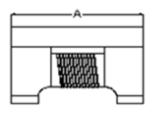
(f) Current Rating Code

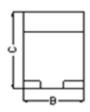
(c) Material Code

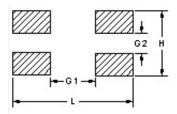
(g) Internal Controlled Number

(d) Inductance Code

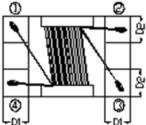
2. Configuration & Dimensions:

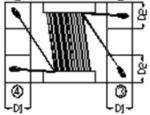






Recommended PCB layout

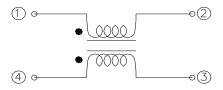




Unit: mm

А	В	С	D1	D2	L	Н	G1	G2
3.20 +0.3/-0.2	2.50±0.2	2.50 Max.	0.55±0.15	0.75±0.2	3.70 Ref.	2.80 Ref.	2.40 Ref.	1.20 Ref.

3. Schematic:

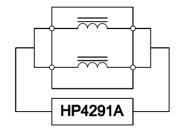


NOTE: Specifications subject to change without notice. Please check our website for latest information.

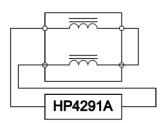


4. Measuring Circuits:

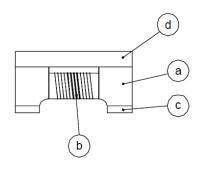
Common mode



Differential mode



5. Material List:



- (a) Core
- (b) Wire
- (c) Terminal
- (d) Upper Plate

6. General Specification:

- (a) Reliability test for this part meets AEC-Q200 standard.
- (b) Operating Temp. : -55°C to +150°C (Including self temperature rise).
- (c) Storage Temp.: -55°C to +150°C (on board).
- (d) Storage Condition (Component in its packaging)

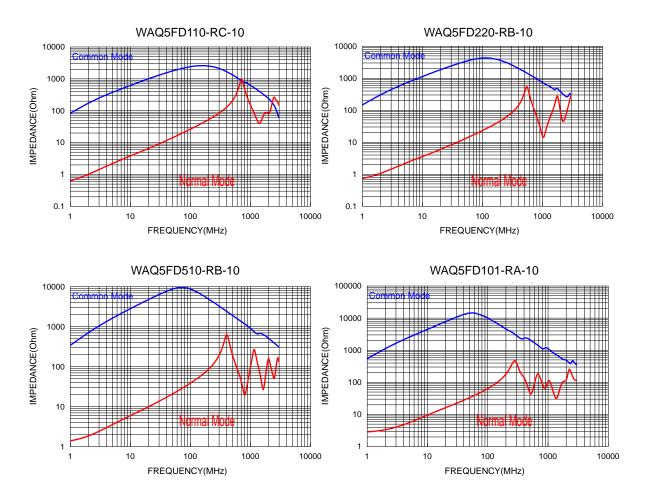
i) Temperature: Less than 40°C

ii) Humidity: 60% RH

7. Electrical Characteristics:

Part Number	Common mode Impedance (Ω) [10MHz]		Inductance (uH)+50/-30%	DCR (Ω) Max.	Rated Current (mA)	Rated Volt (Vdc) Max.	IR (MΩ) Min.
	Min.	Тур.	[0.1V/100K]	ividX.	Max.	IVIAX.	IVIII I.
WAQ5FD110-RC-10	300	550	11	0.4	300	80	10
WAQ5FD220-RB-10	500	1100	22	0.5	250	80	10
WAQ5FD510-RB-10	1000	2600	51	0.7	200	80	10
WAQ5FD101-RA-10	2200	5100	100	1.5	150	80	10

8. Characteristics Curves:



NOTE: Specifications subject to change without notice. Please check our website for latest information.



9. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

9-1 Solder Re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

9-2 Soldering Iron (Figure 2)

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note

- a) Preheat circuit and products to 150°C.
- b) 350°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.

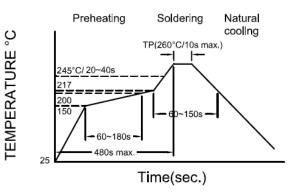


Figure 1. : Re-flow Soldering time 3 times Max.

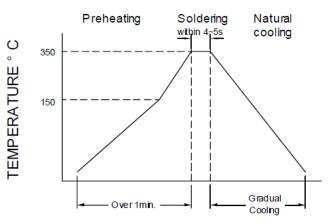
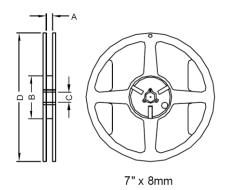
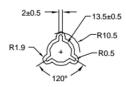


Figure 2. : Iron Soldering time 1 times Max.

10. Packaging Information:

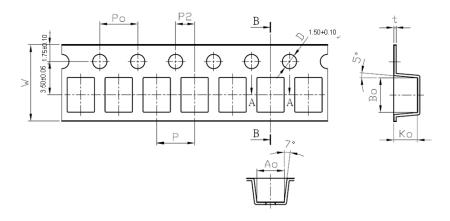
10-1 Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0 ± 0.5	60.0 ± 2.0	13.5 ± 0.5	178.0 ± 2.0

10-2 Tape Dimension



Size	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)	W(mm)	t(mm)
WAQ5FD	4.00±0.10	4.00±0.10	2.00±0.05	3.65±0.10	2.88±0.10	2.50±0.10	8.00±0.10	0.26±0.05

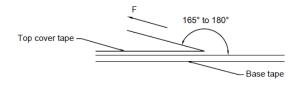
10-3 Packaging Quantity

Chip Size	WAQ5FD		
Chip/Reel	2,000		
Inner Box	10,000		
Middle Box	50,000		
Carton	100,000		

NOTE: Specifications subject to change without notice. Please check our website for latest information.



10-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.